

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A back electrode electronic part comprising:

a main body; ~~including~~

a circuit; and

electrodes arranged ~~for solder bumps on a~~ an outer back surface ~~portion of said electronic part and connected to said circuit~~ of the main body; wherein:

the electrodes comprise integration possible electrodes and general electrodes;

a plurality of the said integration possible electrodes are arranged adjacently to each other to form a group of integration possible electrodes ~~into groups of electrodes at portions of the electrode arrangement;~~

~~said groups~~ the group of integration possible electrodes ~~are provided for~~ is connected to a single first solder bump;

each of the general electrodes are individually connected to single second solder bumps;

the first solder bump ~~which~~ is larger than each of the second solder bumps ~~for said electrodes arranged other than in said groups of electrodes; and~~

~~said groups of~~ each of the integration possible electrodes that are part of the group of integration possible electrodes ~~includes electrodes having~~ have a substantially same potential level when said circuit operates.

2. (Currently Amended) A back electrode electronic part according to claim 1, wherein said electrodes are arranged in a matrix, and said ~~groups~~ group of integration possible electrodes ~~are~~ is arranged at a corner portions of the matrix.

3. (Currently Amended) A back electrode electronic part according to claim 1, wherein one of the integration possible electrodes that are part of said group of integration possible electrodes ~~includes~~ comprises a non-contact electrode which is not connected to said circuit.

4. (Currently Amended) A back electrode electronic part according to claim 1, wherein one of said integration possible electrodes that are part of said group of integration possible electrodes comprises ~~is~~ a signal electrode.

5. (Currently Amended) A back electrode electronic part according to claim 1, wherein one of said integration possible electrodes that are part of said group of integration possible electrodes comprises ~~is~~ a ground potential electrode.

6. (Currently Amended) A back electrode electronic part according to claim 1, wherein one of said integration possible electrodes that are part of said group of integration possible electrodes comprises ~~is~~ a power supply potential electrode.

7. (Previously Presented) An electronic assembly comprising:

a back electrode electronic part comprising:

a main body; ~~including~~

a circuit, and

electrodes arranged on a an outer back surface ~~portion of said electronic part and~~

~~connected to said circuit~~ of the main body, wherein:

~~said electrodes are arranged into groups of electrodes at portions of the electrode~~

~~arrangement;~~

the electrodes comprise integration possible electrodes and general electrodes;

a plurality of the integration possible electrodes are arranged adjacently to each other to

form a group of integration possible electrodes;

~~said groups of~~ each of the integration possible electrodes that are part of the group of

integration possible electrodes ~~includes electrodes having~~ have a substantially same potential

level when said circuit operates;

said electronic assembly further comprising:

a printed circuit board ~~having;~~ and

substrate electrodes arranged on an outer surface of the printed circuit board, wherein:

the substrate electrodes comprising a first substrate electrode and second substrate

electrodes;

~~corresponding to said electrodes provided for said electronic part, wherein one of said~~

~~substrate electrodes as a first substrate electrode is provided for each of said groups of electrodes,~~

~~and said substrate electrodes as second substrate electrodes other than said first substrate electrodes are provided for said electrodes of said electronic part other than in said groups of electrodes; and~~

~~solder bumps including first solder bumps connected with said groups~~ group of integration possible electrodes and said first substrate electrodes electrode are connected to a single first solder bump;

~~and second solder bumps connected with each of said general electrodes and each of said second substrate electrodes and said electrodes of said electronic part other than said groups of electrodes~~ are individually connected to single second solder bumps; and

said first solder bump is larger than each of the second solder bumps.

8. (Currently Amended) A back electrode electronic part according to claim 7, wherein said electrodes of said back electrode electronic part are arranged in a matrix, and said ~~groups~~ group of integration possible electrodes are is arranged at a corner portions of the matrix.

9. (Currently Amended) ~~A back electrode electronic part~~ An electronic assembly according to claim 7, wherein one of said ~~integrated~~ integration possible electrodes that are part of said group of integration possible electrodes comprises ~~is~~ a non-contact electrode which is not connected to said circuit.

10. (Currently Amended) ~~A back electrode electronic part~~ An electronic assembly according to claim 7, wherein one of said ~~integrated~~ integration possible electrodes that are part of said group of integration possible electrodes comprises ~~is~~ a signal electrode.

11. (Currently Amended) ~~A back electrode electronic part~~ An electronic assembly according to claim 7, wherein one of said integration possible electrodes that are part of said group of integration possible electrodes comprises ~~is~~ a ground potential electrode.

12. (Currently Amended) ~~A back electrode electronic part~~ An electronic assembly part according to claim 7, wherein one of said integration possible electrodes that are part of said group of integration possible electrodes comprises ~~is~~ a power supply potential electrode.

13. (Currently Amended) A back electrode electronic part according to claim 1, wherein said group of integration possible electrodes ~~are~~ is directly connected to said first solder bump.

14. (Currently Amended) A back electrode electronic part according to claim 1, wherein said electrodes arranged ~~for solder bumps~~ on an outer surface of the main body of the back electrode electronic part protrude from said back electrode electronic part so as to support said first and second solder bumps.

15. (Currently Amended) A back electrode electronic part according to claim 1, wherein ~~said electrodes arranged for solder bumps are provided on the rearmost~~ the outer surface of the main body is a rearmost surface of said back electrode electronic part.

16. (Currently Amended) ~~A back electrode electronic part~~ An electronic assembly according to claim 7, wherein said ~~groups~~ group of integration possible electrodes are directly connected to said first solder bump.

17. (Currently Amended) ~~A back electrode electronic part~~ An electronic assembly according to claim 7, wherein said electrodes arranged for solder bumps on an outer surface of the main body of the back electrode electronic part protrude from said back electrode electronic part so as to support said first and second solder bumps.

18. (Currently Amended) ~~A back electrode electronic part~~ An electronic assembly according to claim 7, wherein ~~said electrodes arranged for solder bumps are provided on the rearmost~~ the outer surface of the main body is a rearmost surface of said back electrode electronic part.

19. (Previously Presented) A back electrode electronic part comprising:
at least two first electrodes positioned on a an outer rear surface of said electronic part ~~so as to be~~ and connected to a first solder bump;

at least one second electrode positioned on a the outer rear surface of said electronic ~~so as~~
~~to be~~ and connected to a second solder bump; wherein

said first solder bump has a larger lateral cross section than said second solder bump; and
each of said first electrodes and second electrode are arranged in a matrix on said rear
surface of said electronic part so that the first electrodes are spaced apart by the same distance
that the second electrode is spaced apart from a nearest one of the first electrodes.

20. (Cancelled)

21. (Previously Presented) A back electrode electronic part comprising:

a main body including a circuit; and

electrodes arranged for solder bumps and supported on a an outer back surface portion of
said electronic part and connected to said circuit; wherein

said electrodes are arranged into groups of electrodes at portions of the electrode
arrangement;

at least one of said groups of electrodes is connected to a first solder bump which is
larger than second solder bumps connected to said electrodes arranged other than in said groups
of electrodes;

the electrodes arranged other than in said groups of electrodes are each connected to only
one second solder bump; and

said groups of electrodes include electrodes having a substantially same potential level when said circuit operates.

22. (Cancelled)

23. (New) A back electrode electronic part according to claim 1, wherein each of the electrodes are the same size.

24. (New) A back electrode electronic part according to claim 1, wherein a first distance between a first and second one of the plurality of integration electrodes forming the group of integration possible electrodes is the same as a second distance between the first one of the plurality of integration electrodes and a nearest one of the general electrodes.

25. (New) A back electrode electronic part according to claim 1, wherein four integration electrodes form the group of integration possible electrodes.

26. (New) A back electrode electronic part according to claim 1, wherein three integration electrodes form the group of integration possible electrodes.

27. (New) A back electrode electronic part according to claim 1, wherein a first and second one of said integration possible electrodes that are part of said group of integration possible electrodes comprises a ground electrode and a non-contact electrode, respectively.

28. (New) A back electrode electronic part according to claim 1, wherein a first and second one of said integration possible electrodes that are part of said group of integration possible electrodes comprises a signal electrode and a non-contact electrode, respectively.

29. (New) A back electrode electronic part according to claim 1, wherein a first and second one of said integration possible electrodes that are part of said group of integration possible electrodes comprises a power electrode and a non-contact electrode, respectively.

30. (New) An electronic assembly according to claim 7, wherein each of the electrodes of the back electrode electronic part are the same size.

31. (New) An electronic assembly according to claim 7, wherein a first distance between a first and second one of the plurality of integration electrodes of the back electrode electronic part forming the group of integration possible electrodes is the same as a second distance between the first one of the plurality of integration electrodes and a nearest one of the general electrodes.

32. (New) An electronic assembly according to claim 7, wherein four integration electrodes of the back electrode electronic part form the group of integration possible electrodes.

33. (New) An electronic assembly according to claim 7, wherein three integration electrodes of the back electrode electronic part form the group of integration possible electrodes.

34. (New) An electronic assembly according to claim 7, wherein a first and second one of said integration possible electrodes of the back electrode electronic part that are part of said group of integration possible electrodes comprises a ground electrode and a non-contact electrode, respectively.

35. (New) An electronic assembly according to claim 7, wherein a first and second one of said integration possible electrodes of the back electrode electronic part that are part of said group of integration possible electrodes comprises a signal electrode and a non-contact electrode, respectively.

36. (New) An electronic assembly according to claim 7, wherein a first and second one of said integration possible electrodes of the back electrode electronic part that are part of said group of integration possible electrodes comprises a power electrode and a non-contact electrode, respectively.

37. (New) An electronic assembly according to claim 7, wherein said first substrate electrode of said printed circuit board is larger than each of said second electrodes of said printed circuit board.